

Guidelines for validation of the integrity and adequacy of the Technology Transfer Documents (TTD) for inclusion in TT&CD repository

TT&CD is entrusted to maintain the repository of the technical know-how developed by various scientists and engineers. This not only ensures that the technology developed is available in future in the form of drawings and documentation but also the product could be purchased from the transferees of the technology. Further, the response received through the advertisement of the available technology on BARC website also reveals the true worth of the know-how, particularly in case of non DAE applications, encouraging application oriented development.

Director, BARC has directed TT&CD to ensure high standard of technology transfer documents, commensurate with the prestige of our Centre. Therefore the contributing Divisions may kindly take care to ensure accurate, complete and meticulous preparation of technology documentation before intimating new technology for transfer. This is mandatory since no prototype is provided to the transferee on transfer of technology, it rules out finding any additional information by reverse engineering.

A typical technology transfer package must consist of following components:

1. All engineering drawings in CAD as well as in pdf (Pdf shall be on actual size i. e. A0, A1 as the case may be) in DVD. The drawings should have BARC signature nameplate with tolerances and scale mentioned at appropriate place. Detailed Drawings, if generated by fabricators, should also be submitted with BARC nameplate and approving authority's signature.
2. Complete Bill of Material on the drawing must be provided along with a consolidated list. The list of vendors for sourcing the material is required, if it is not general.
3. Electronic circuit drawings shall be submitted with PCB layout with Gerber files and test procedure. These shall be CAD as well as in pdf files (in actual size). Specifications of all components including type of PCB recommended and mechanical layout for mounting Heat-sink, fans, transformer etc. is to be provided. Test procedure must be provided.
4. Cable layout and connector specifications should be provided with tag labels of each wire in the cable along with signal identity.
5. Software flow chart, source code (only softcopy), compiler used (with version and library files required), Operating system and hardware details, standalone (independently executable) executable binary files (in softcopy)
6. High resolution photographs, brochure, leaflet and write-up for preparing web-advertisements and posters size (3'x4').
7. List of prospective manufacturers who may be contacted.

8. A typical Technology Transfer Document accompanying above material should contain, in general, following chapters:
 - A. Executive Summary [Overview of the product, comparison with contemporary technology, user profile, candidate transferee's skill requirement, infrastructure requirement AND what does this document offer]
 - B. Content
 - C. List of Figures, Photographs
 - D. Technical specification
 - E. Introduction
 - F. Principle and concept development
 - G. Description of major assemblies:
 - a. Assembly {NAME}-
 - i. purpose,
 - ii. specification,
 - iii. schematic and
 - iv. reference to the engg. drawing
 - v. description of each component of the assembly and reference to the drawing.
 - vi. Assembly and testing procedure
 - b. Assembly {NAME} –Continue as above for each assembly (Including electronic console, power supply)
 - H. Erection, installation and commissioning procedure
 - I. Test procedures
 - J. Safety precautions
 - K. Index
 - L. Enclosures: As mentioned in points 1-5.

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